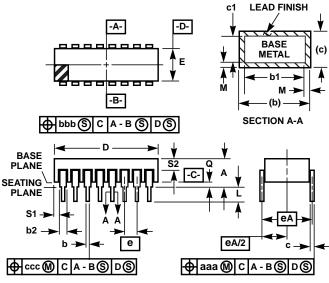
Ceramic Dual-In-Line Metal Seal Packages (SBDIP)



NOTES:

- 1. Index area: A notch or a pin one identification mark shall be located adjacent to pin one and shall be located within the shaded area shown. The manufacturer's identification shall not be used as a pin one identification mark.
- 2. The maximum limits of lead dimensions b and c or M shall be measured at the centroid of the finished lead surfaces, when solder dip or tin plate lead finish is applied.
- 3. Dimensions b1 and c1 apply to lead base metal only. Dimension M applies to lead plating and finish thickness.
- Corner leads (1, N, N/2, and N/2+1) may be configured with a partial lead paddle. For this configuration dimension b3 replaces dimension b2.
- 5. Dimension Q shall be measured from the seating plane to the base plane.
- 6. Measure dimension S1 at all four corners.
- 7. Measure dimension S2 from the top of the ceramic body to the nearest metallization or lead.
- 8. N is the maximum number of terminal positions.
- 9. Braze fillets shall be concave.
- 10. Dimensioning and tolerancing per ANSI Y14.5M 1982.
- 11. Controlling dimension: INCH.

D24.6 MIL-STD-1835 CDIP2-T24 (D-3, CONFIGURATION C)
24 LEAD CERAMIC DUAL-IN-LINE METAL SEAL PACKAGE

	INCHES		MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES
А	-	0.225	-	5.72	-
b	0.014	0.026	0.36	0.66	2
b1	0.014	0.023	0.36	0.58	3
b2	0.045	0.065	1.14	1.65	-
b3	0.023	0.045	0.58	1.14	4
С	0.008	0.018	0.20	0.46	2
c1	0.008	0.015	0.20	0.38	3
D	-	1.290	-	32.77	-
Е	0.500	0.610	12.70	15.49	-
е	0.100 BSC		2.54 BSC		-
eA	0.600 BSC		15.24 BSC		-
eA/2	0.300 BSC		7.62 BSC		-
L	0.120	0.200	3.05	5.08	-
Q	0.015	0.075	0.38	1.91	5
S1	0.005	-	0.13	-	6
S2	0.005	-	0.13	-	7
α	90 ⁰	105 ⁰	90 ⁰	105 ⁰	-
aaa	-	0.015	-	0.38	-
bbb	-	0.030	-	0.76	-
CCC	-	0.010	-	0.25	-
М	-	0.0015	-	0.038	2
Ν	24		24		8

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